

December 2008

IDERFET

FCH20N60 / FCA20N60 / FCA20N60_F109

600V N-Channel MOSFET

Features

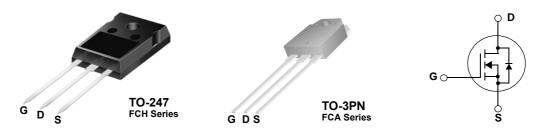
- 650V @T_J = 150°C
- Typ. Rds(on)=0.15Ω
- Ultra low gate charge (typ. Qg=55nC)
- Low effective output capacitance (typ. Coss.eff=110pF)
- 100% avalanche tested
- · RoHS Compliant



Description

SuperFETTM is, Fairchild's proprietary, new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance.

This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. Consequently, SuperFET is very suitable for various AC/DC power conversion in switching mode operation for system miniaturization and higher efficiency.



Absolute Maximum Ratings

Symbol	Parameter		FCH20N60	FCA20N60	Unit
V _{DSS}	Drain-Source Voltage		600		V
I _D	Drain Current - Continuous (T _C = 25°C) - Continuous (T _C = 100°C)		20 12.5		A A
I _{DM}	Drain Current - Pulsed	(Note 1)	6	0	А
V _{GSS}	Gate-Source voltage		± 30		V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		690		mJ
I _{AR}	Avalanche Current (Note		20		Α
E _{AR}	Repetitive Avalanche Energy (Note 1)		20.8		mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		4.5		V/ns
P_{D}	Power Dissipation $(T_C = 25^{\circ}C)$ - Derate above 25°C		208 1.67		W W/°C
$T_{J,}T_{STG}$	Operating and Storage Temperature Range		-55 to +150		°C
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300		°C

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.6	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink 0.24			
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		41.7	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FCH20N60	FCH20N60	TO-247	-	-	30
FCA20N60	FCA20N60	TO-3PN	-	-	30
FCA20N60	FCA20N60_F109	TO-3PN	-	-	30

Electrical Characteristics $T_C = 25$ °C unless otherwise noted

Symbol	Parameter	Conditions	Min	Тур	Max	Units
Off Charac	teristics			!		
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A, T_J = 25^{\circ}C$	600			V
		$V_{GS} = 0V, I_D = 250\mu A, T_J = 150^{\circ}C$		650		V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C		0.6		V/°C
BV _{DS}	Drain-Source Avalanche Breakdown Voltage	$V_{GS} = 0V, I_{D} = 20A$		700		V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 600V, V_{GS} = 0V$ $V_{DS} = 480V, T_{C} = 125^{\circ}C$			1 10	μA μA
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30V, V _{DS} = 0V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30V$, $V_{DS} = 0V$			-100	nA
On Charac	teristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 10A		0.15	0.19	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40V, I _D = 10A (Note 4)		17		S
Dynamic C	haracteristics					
C _{iss}	Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$		2370	3080	pF
C _{oss}	Output Capacitance	f = 1.0MHz		1280	1665	pF
C _{rss}	Reverse Transfer Capacitance			95		pF
C _{oss}	Output Capacitance	$V_{DS} = 480V, V_{GS} = 0V, f = 1.0MHz$		65	85	pF
C _{oss} eff.	Effective Output Capacitance	$V_{DS} = 0V$ to 400V, $V_{GS} = 0V$		165		pF
Switching	Characteristics			•	•	
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 300V, I_D = 20A$		62	135	ns
t _r	Turn-On Rise Time	$R_G = 25\Omega$		140	290	ns
t _{d(off)}	Turn-Off Delay Time			230	470	ns
t _f	Turn-Off Fall Time	(Note 4, 5)		65	140	ns
Qg	Total Gate Charge	$V_{DS} = 480V, I_{D} = 20A$		75	98	nC
Q_{gs}	Gate-Source Charge	V _{GS} = 10V		13.5	18	nC
Q _{gd}	Gate-Drain Charge	(Note 4, 5)		36		nC
Drain-Sour	ce Diode Characteristics and Maximur	n Ratings		ı		
I _S	Maximum Continuous Drain-Source Dio	de Forward Current			20	Α
I _{SM}	Maximum Pulsed Drain-Source Diode F	orward Current			60	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0V, I _S = 20A			1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 20A		530		ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s$ (Note 4)		10.5		μС

NOTES:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. I_{AS} = 10A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25 $^{\circ}C$
- 3. I_{SD} \leq 20A, di/dt \leq 200A/µs, V_{DD} \leq BV_DSS, Starting T_J = 25°C
- 4. Pulse Test: Pulse width $\leq 300 \mu s, \ Duty \ Cycle \leq 2\%$
- 5. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

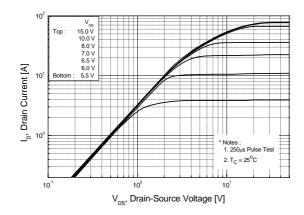


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

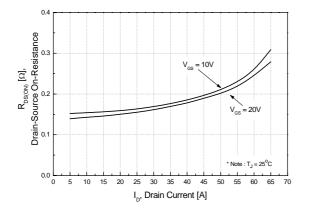


Figure 5. Capacitance Characteristics

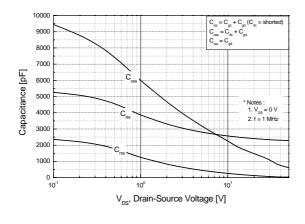


Figure 2. Transfer Characteristics

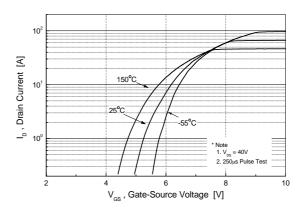


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

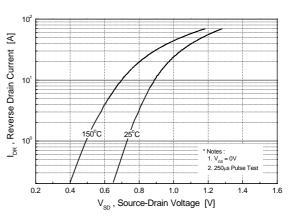
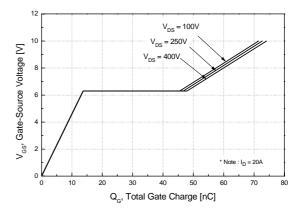


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

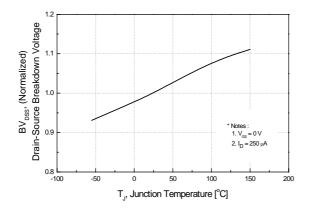


Figure 8. On-Resistance Variation vs. Temperature

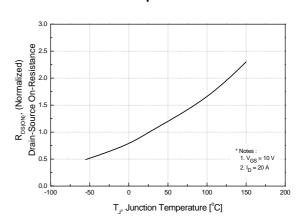


Figure 9. Maximum Safe Operating Area

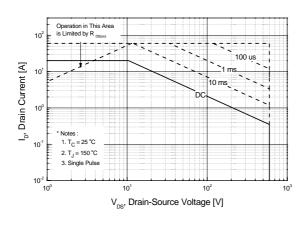


Figure 10. Maximum Drain Current vs. Case Temperature

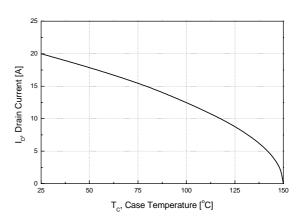
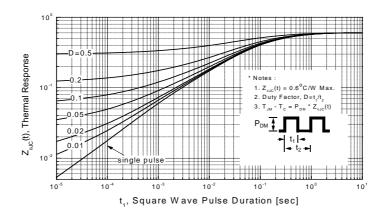
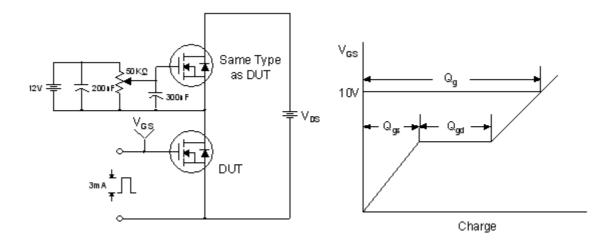


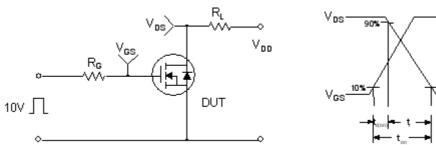
Figure 11. Transient Thermal Response Curve



Gate Charge Test Circuit & Waveform

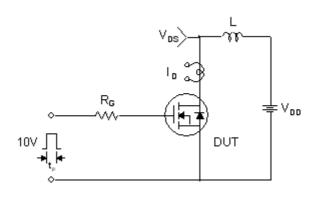


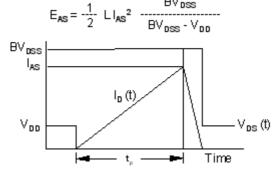
Resistive Switching Test Circuit & Waveforms



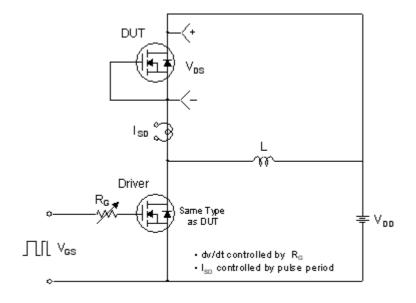
V_{GS} 10%

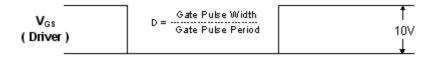
Unclamped Inductive Switching Test Circuit & Waveforms

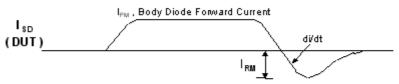




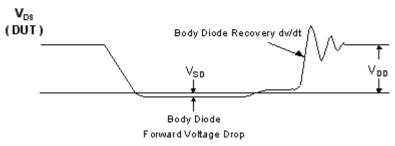
Peak Diode Recovery dv/dt Test Circuit & Waveforms





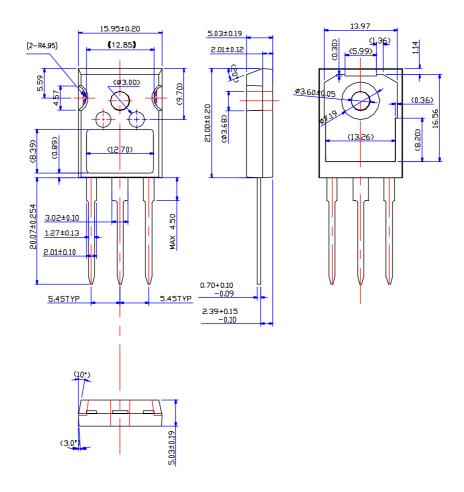


Body Diode Reverse Current

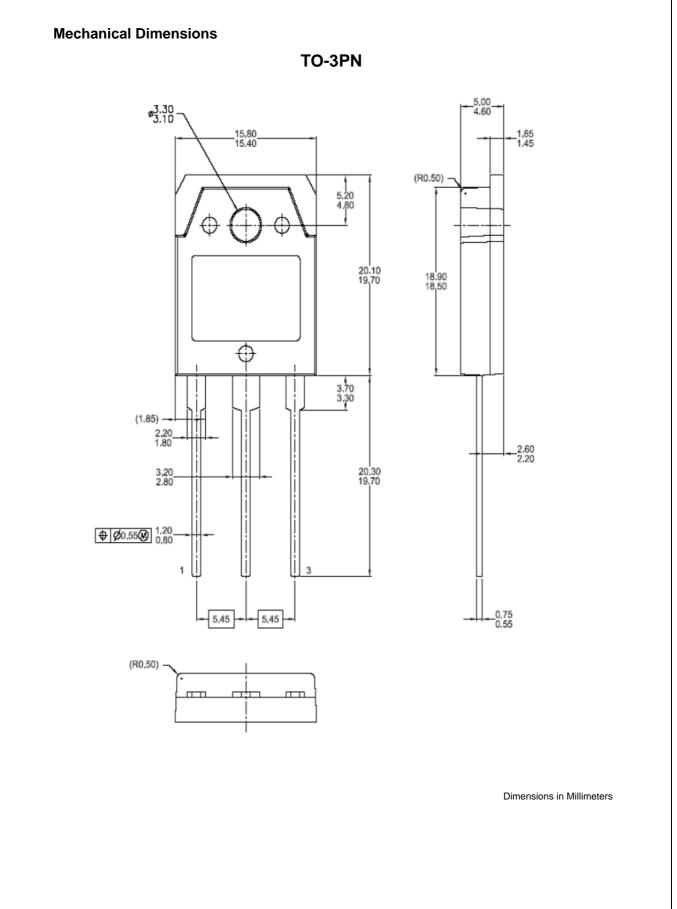


Mechanical Dimensions

TO-247AD (FKS PKG CODE 001)



Dimensions in Millimeters







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